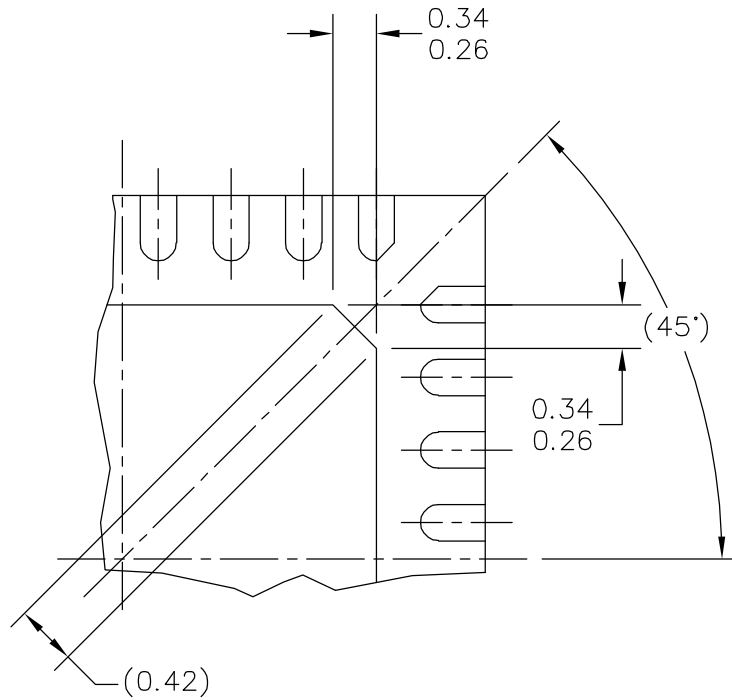
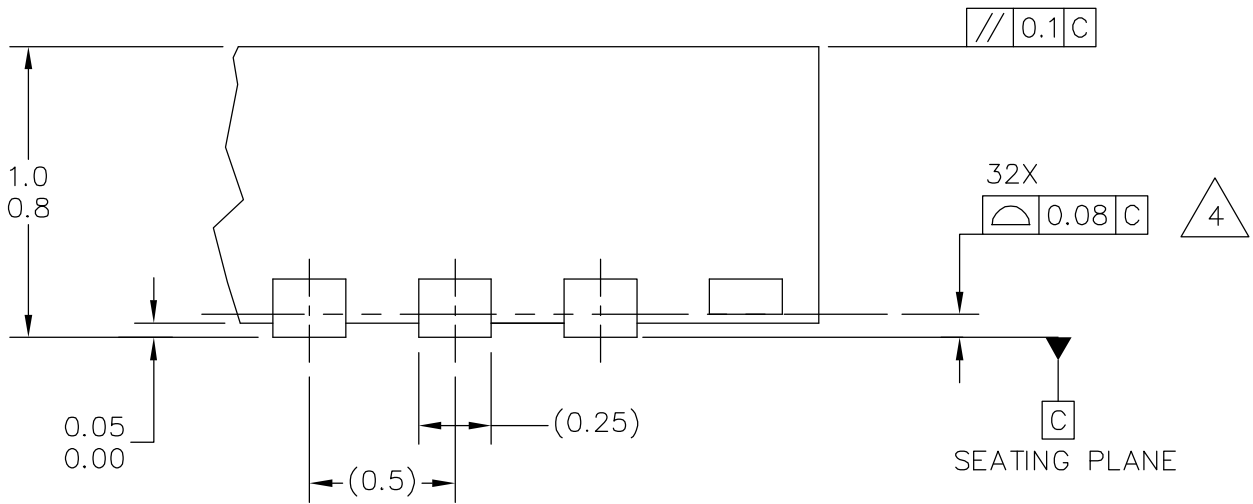


© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 32 TERMINAL, 0.50 PITCH (5 X 5 X 1) 3.5 X 3.5 EP, CASE OUTLINE	DOCUMENT NO: 98ASA10800D	REV: A
	STANDARD: NON-JEDEC	
	SOT617-20	17 MAR 2016



DETAIL M
PIN 1 BACKSIDE IDENTIFIER




DETAIL G
VIEW ROTATED 90°CW

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 32 TERMINAL, 0.50 PITCH (5 X 5 X 1) 3.5 X 3.5 EP, CASE OUTLINE		DOCUMENT NO: 98ASA10800D	REV: A
		STANDARD: NON-JEDEC	
		SOT617-20	17 MAR 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. RADIUS ON TERMINAL IS OPTIONAL.
4.  COPLANARITY APPLIES TO LEADS, AND DIE ATTACH PAD.
5. MINIMUM METAL GAP SHOULD BE 0.2 MM.

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 32 TERMINAL, 0.50 PITCH (5 X 5 X 1) 3.5 X 3.5 EP, CASE OUTLINE		DOCUMENT NO: 98ASA10800D	REV: A
		STANDARD: NON-JEDEC	
		SOT617-20	17 MAR 2016